

**PMP9204 Rev B Bill of Materials**

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
IPC?	1		Printed Circuit Board		PMP9204	Any
C1, C2	2	6.8uF	CAP, AL, 6.8uF, 400V, +/-20%, TH	CAPPR5-10x16	UCA2G6R8MPD1TD	Nichicon
C3	1	10uF	CAP, CERM, 10uF, 50V, +/-10%, X5R, 1206_190	1206_190	CGA5L3X5R1H106K160AB	TDK
C4, C5	2	220uF	CAP ALUM 220UF 6.3V 20% RADIAL	RCAP, 6.3x8mm	APSA6R3ELL221MFA5G	United Chemi-Con
C6, C7	2	1uF	CAP, CERM, 1uF, 10V, +/-10%, X5R, 0402	0402	GRM155R61A105KE15D	MuRata
C10	1	2200pF	CAP, CERM, 2200pF, 250V, +/-20%, KY, Radial D8x5mm	Radial D8x5mm	DE2E3KY222MA2BM01	MuRata
C13	1	0.22uF	CAP, CERM, 16V, +/-10%, X7R, 0402	0402	STD	STD
C100	1	0.01uF	CAP, CERM, 25V, +/-10%, X7R, 0402	0402	STD	STD
D1	1	600V	Diode, Switching-Bridge, 600V, 0.5A, MiniDIP	MiniDIP	RH06-T	Diodes Inc.
D2	1	90V	Diode, TVS, Uni, 90V, 400W, SMA	SMA	SMAJ90A	Littelfuse
D3	1	1.05V	DIODE GEN PURPOSE 1000V 1A SMA	SMA	MRA4007	ON Semiconductor
D4	1	45V	Diode, Super Barrier Rectifier, 45V, 10A, PowerDi5	PowerDi5	SBR10U45SP5	Diodes Inc.
D5	1	100V	Diode, Ultrafast, 100V, 0.25A, SOD-323	SOD-323	BAS316,115	NXP Semiconductor
F1	1		Fuse, 0.5A, 250V, TH	8.35x7.7x4mm	RST 500	Bel Fuse
J1	1		Connector, Receptable, USB Type A, Vertical, TH	Vertical USB Type A	1002-021-01000	CnC Tech
L1	1	100uH	Inductor, Drum Core, Ferrite, 100uH, 0.32A, 3.5 ohm, SMD	ME3220	ME3220-104KLB	Coilcraft
L2	1	1uH	Inductor, Shielded, Composite, 1uH, 2.5A, 0.04 ohm, SMD	3x1.2x3mm	XFL3012-102MEB	Coilcraft
Q1	1	600V	MOSFET N-CH 600V 2.5A TO252	DPAK	AOD3N60	Alpha & Omega Semiconductor Inc
R3	1	49.9	RES, 49.9 ohm, 1%, 0.25W, 1206	1206	CRCW120649R9FKEA	Vishay-Dale
R4	1	49.9	RES, 1%, 0.063W, 0402	0402	STD	STD
R5	1	0	RES, 1%, 0.063W, 0402	0402	STD	STD
R6, R12	2	1.00k	RES, 1%, 0.063W, 0402	0402	STD	STD
R9	1	2.00k	RES, 1%, 0.063W, 0402	0402	STD	STD
R10	1	0.91	RES, 1%, 0.125W, 0805	0805	STD	STD
R11	1	1.78k	RES, 1%, 0.063W, 0402	0402	STD	STD
R14, R16	2	30.1k	RES, 1%, 0.063W, 0402	0402	STD	STD
R15	1	133k	RES, 1%, 0.063W, 0402	0402	STD	STD
R17, R103	2	10k	RES, 1%, 0.063W, 0402	0402	STD	STD
R101, R102	2	499	RES, 1%, 0.063W, 0402	0402	STD	STD
T1	1	435 uH	Transformer, 430uH, TH	760x670x730mil	RLTI-1067	Renco Electronics
TP1, TP2	2	White	Test Point, TH, Multipurpose, White	Keystone5012	5012	Keystone
TP3	1	Red	Test Point, Miniature, Red, TH	Red Miniature Testpoint	5000	Keystone
TP4	1	Black	Test Point, Miniature, Black, TH	Black Miniature Testpoint	5001	Keystone
U1	1		Constant-Voltage, Constant-Current Flyback Controller Using Opto-Coupler Feedback, D0007A	D0007A	UCC28740D	Texas Instruments
U2	1		PRECISION PROGRAMMABLE REFERENCE, DBZ0003A	DBZ0003A	TL431AIDBZ	Texas Instruments
U3	1		Opto-Isolator, 1 Channel, SMT	DIP-4	LTV-817S	Lite-On

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